

NY32

Highest Demanding Finishing Processes



Automotive



Mobility



IoT/IoV & Optoelectronics



Computing & Network



Industrial & Medical



Consumer

Productivity

- Up to 30,000 UPH
- Complete Finishing Solution
 - Full Vision inspection
 - Test Contacting
 - Electrical Tester (Discrete)
 - Auto Reel Changer

Flexibility

- Tube / Metal Magazine / Bowl Feeder
- Up to 16 Test Sites
- 6 Sides inspection
- Tape and Reel/Tube / Tray Output
- In-Tape inspection with Auto-Reject and Replacement
- Tube /Tray / Bulk Reject
- Wide applicable device range 0.3 x 0.6 mm to 17 x 17 mm
 - Discrete, Power Discrete, DFN/QFN, SOIC, LED, BGA, MEMS, Bare Die, Bumped Die

- 32-position Turret Test and Scan
- Autonomous operation and productivity
- Automotive KGD
- Comprehensive Cohu NV-Core Inspection System
 - 3D Flex® for True Ball/Bump co-planarity
 - Full 6 Sides inspection

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Specifications

Platform

Device Range

- Discrete Leaded: 1 x 0.6 to 6 x 6 mm/thickness ≥ 0.38 mm
- Power Discrete: 5 x 5 to 10 x 30 mm/thickness ≥ 0.38 mm
- Discrete DFN: 0.3 x 0.6 to 12 x 12 mm/thickness ≥ 0.30 mm
- QFN: 1 x 1 to 12 x 12 mm/thickness ≥ 0.30 mm
- SOIC: 3 x 4.9 to 17 x 17 mm/thickness ≥ 0.90 mm
- LED: 1.5 x 1.5 to 12 x 12 mm/thickness ≥ 0.30 mm

Contacting Force

- Up to 7N independent Z axis
- Up to 27N high force independent Z axis (optional)
- Up to 50N pneumatic plunger (optional)

Index Time

- Down to 80 ms, depending on device and process

Performance Characteristics

- Discrete Leaded: up to 30,000 UPH
- Power Discrete: up to 20,000 UPH
- Discrete DFN: up to 30,000 UPH
- QFN: up to 30,000 UPH/up to 17,000 UPH with extra pneumatic plunger
- SOIC: up to 25,000 UPH
- LED: up to 35,000 UPH
- MTBA: typ. >2 h
- MTBF: typ. >168 h
- Conversion time: typ. <60 min
- Automatic rejection and replacement in tape (optional)
- 2nd Tape and Reel with flip-flop mode (optional)
- Auto Reel Changer (optional)

User Interface

- Movable Windows-based color touchscreen
- Language: English and Chinese (simplified), other upon request
- Keyboard, mouse (optional)
- Handler status indicator light (green, yellow, red)
- NV-Core Inspection System: dedicated monitor, keyboard, mouse

Interface

- Network: Ethernet capability
- I/O parallel interface for Tester and Laser
- SECS GEM (optional)
- GPIB (optional)

ESD

- According to ANSI / ESD S20.20 / ESD SP10.1
- ESD Class 0 (optional)

Specifications subject to change without notice.

For detailed performance specifications, please contact Cohu.

Facility Requirements

- 110 VAC - 240 VAC 50/60 Hz, One Phase
- 2 kVA / 3.5 kVA with vacuum pump (optional)
- Air Pressure range: 5-10 bar ± 0.5 bar
- Air consumption: 5 m³/hour (typical)
- Vacuum Network: -0.5 Bars $\pm 10\%$
- Consumption: typ. 420 l/min (typical)

Dimensions

- Overall dimension: 0.8 x 0.8 x 1.8 m
- Floor space requirement: 1.3 x 1.0 x 1.8 m
- Weight: net typ. 650 kg/gross typ. 1000 kg

Standards

- CE
- SEMI S2/S8 assessment
- 2006/42/EC Machinery
- 2014/30/EU Electromagnetic compatibility (EMC)
- 2014/35/EU Low voltage directive

Process Capabilities

Input

- Bowl, Tube, Metal Magazine, JEDEC Tray, De-taping

Output

- Tape & Reel, Auto Reel Changer, Wafer output, Tube, JEDEC Tray, LED 64 Bulk Sorting

Processes

- Device Orientation
- Device Flip
- Test Contacting
- Electrical Tester (Discrete)
- LED optical test (ambient and temperature 90°C)
- Laser marking
- 6 Sides Vision inspection
- Bulk, Tube, Dual Tray sorting
- Waffle Pak sorting
- Wafer reject sorting
- Wafer map traceability

NV-Core Vision System

- 1D/2DMC code reader
- 2D/3D Flex[®] ball/bump co-planarity
- Mark, Surface, 5S, Color Vision
- In-Tape, Post Sealing inspection
- LED dedicated solutions

Contactors

- Cohu offers contact sockets for all package versions and applications, i.e. One Touch Socket "High Amps", Flat Test Kelvin, Small Device Kelvin, Pogo pin pocket, LED dedicated solutions